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Fax Cover Sheet

DATE	PAT JUN 13, 2006
TO	KAM AND CUNEO
CC	RON@GHZDATA.COM
FROM	RONALD B. MILLER
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*Return Receipt Requested**1 OF 19**CFC received 3 p. (missing 16 p.)*



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Friday, May 27, 2006

COMMISSIONER FOR PATENTS
PO BOX 1450
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Attn: Kamand Cuneo
Art Unit 2841
RE: 10/601/464
RE: Office Action Summary 4/27/06 from Ishwar Patel
RE: Response to Office Action Summary 11/29/2005
RE: Notice of Non-Compliant Amendment sent on 12/29/05 by D Bell
RE: my Letter and amendment of December 26, 2005

Dear Mr Cuneo,

It appears that Mr. Cuneo is having serious misunderstanding of the subject matter of my patent application

He continues to try to compare my invention of "Method for embedding an air dielectric transmission line in a printed wiring board(PCB)" as used to connect analog and digital circuitry, with MICROWAVE, MMIC MODULES and the like.

Nothing I say on the telephone or write in my answers clears up this his thinking that this is like a modele or MMIC

Now, after several months I find that Tabatabai (US Patent 6924712) which has similar features to my invention has received a patent 2005, even though his application date was much later than mine. It may be that Tabatabai has infringed upon my patent rights even though they are slightly different, in that his electrical traces are on the surface of the PCB while mine are within the PCB.

Accordingly, please ask examiner Benny Lee was the examiner on that patent or someone else who is competent to re-examine this patent.

Yours Sincerely


Ronald B. Miller

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Item 2. The title of the invention is not descriptive(YOU SAY).

Please substitute the following Title: A multi-layer printed circuit board with internal segments of electrical connections suspended in air dielectric.

Item 3.

Claim 1: (Currently amended)

1. A multi-layer printed circuit board (PCB) (see figure 2) with internal signal traces on a thin dielectric layer with said traces on dielectric layers suspended in air between two flat metal plates. Suspension in air is accomplished by indentation of the flat metal plates above and below the trace and a distance away from the edges of the trace, leaving the remainder of the metal away from the indentation to act as a spacer. The indented area is referred to as a "channel". See FIG. 1 for orthogonal view and FIG. 2 for end-on view, with said signal traces connected to vias which penetrate through the PCB to the top and bottom surfaces connecting other electronic components either by through-hole mounting where the via hole is large and a component lead is inserted in the via, or by surface mount connection wherein said metal plates have oversized holes in the metal filled with insulation material larger than the via aligned with each via electrically isolating the via from the plate, and mechanically fixing the position of the via relative to the metal plate, with the via being electrically connected to the signal trace by a pad at the end of the trace aligned with and joined to the via.

Claim 4

Claim 17. (Currently amended)

The PCB of claim 1 wherein laminating metal to metal may use an adhesive coating or an adhesive sheet. The adhesive will have no effect on electrical high speed performance because the thin dielectric of the adhesive with wide metal plates forms a high frequency capacitive short from top to bottom plates.

Item 4

(Insert Concluding claim per paragraph 2 of 35 U.S.C. 112).

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